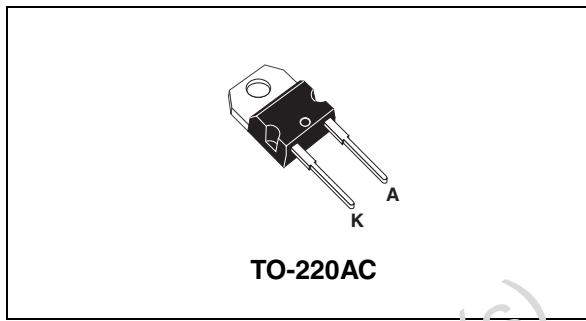


FAST RECOVERY RECTIFIER DIODES

Table 1: Main Product Characteristics

$I_{F(AV)}$	6 A
V_{RRM}	800 V
T_j	150°C
V_F (max)	1.4 V
t_{rr} (max)	300 ns



FEATURES AND BENEFITS

- High voltage capability
- Fast and soft recovery

DESCRIPTION

Single chip rectifier suited for power conversion and polarity protection applications.

This device is packaged in TO-220AC.

Table 2: Order Code

Part Number	Marking
BYT71-800	BYT71800

Table 3: Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	800	V
$I_{F(RMS)}$	RMS forward voltage	12	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	6	A
I_{FSM}	Surge non repetitive forward current $t_p = 10\text{ms}$ sinusoidal	90	A
T_{stg}	Storage temperature range	-65 to + 150	°C
T_j	Maximum operating junction temperature	150	°C

Table 4: Thermal Resistance

Symbol	Parameter	Value (max.)	Unit
R _{th(j-c)}	Junction to case	2.3	°C/W

Table 5: Static Electrical Characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I _R *	Reverse leakage current	T _j = 25°C	V _R = V _{RRM}			20	µA
		T _j = 100°C				1	mA
V _F **	Forward voltage drop	T _j = 25°C	I _F = 6A			1.4	V
		T _j = 100°C				1.3	

Pulse test: * tp = 5 ms, δ < 2%

** tp = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation: P = 1.15 x I_{F(AV)} + 0.025 I_F² (RMS)**Table 6: Recovery Characteristics**

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
t _{rr}	Reverse recovery time	T _j = 25°C	I _F = 1A dl _F /dt = -15 A/µs V _R = 30V			300	ns

Figure 1: Average forward power dissipation versus average forward current

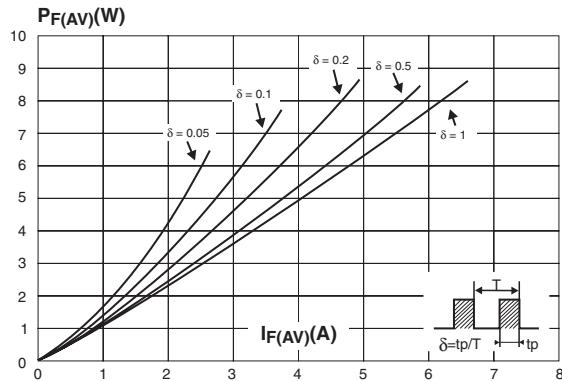


Figure 3: Relative variation of thermal impedance junction to case versus pulse duration

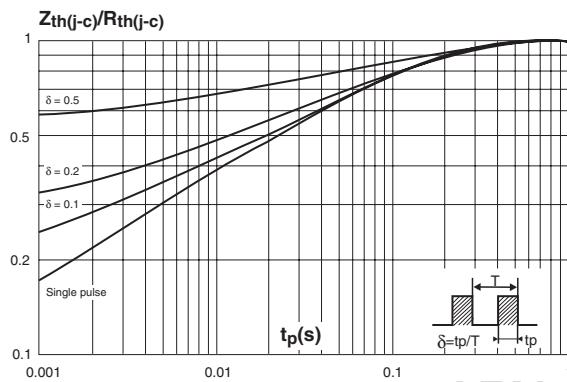


Figure 5: Peak reverse current versus dI_F/dt (90% confidence)

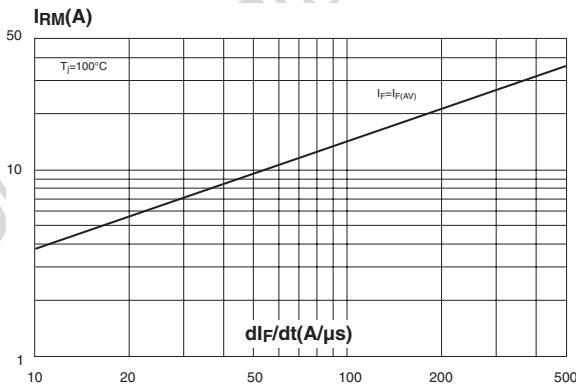


Figure 2: Average current versus ambient temperature ($\delta = 0.5$)

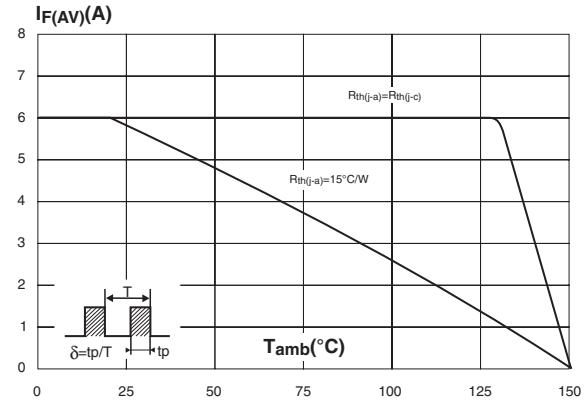


Figure 4: Peak current versus form factor

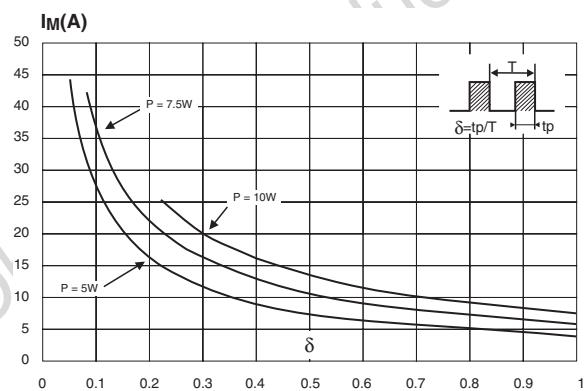


Figure 6: Forward voltage drop versus forward current (maximum values)

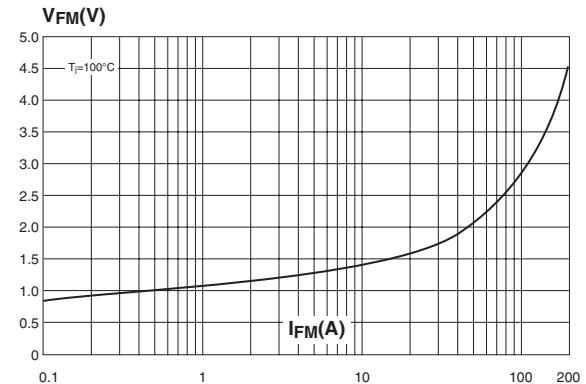


Figure 7: Recovery charges versus dI_F/dt (90% confidence)

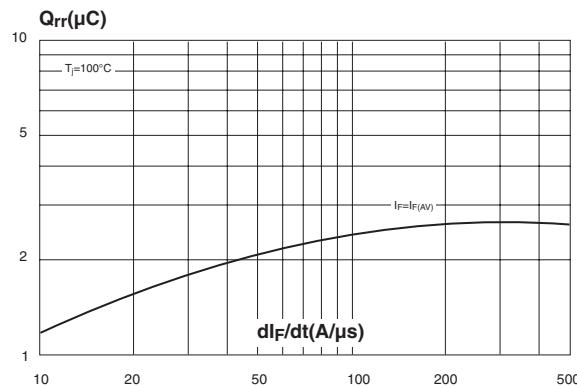


Figure 9: Recovery time versus dI_F/dt (90% confidence)

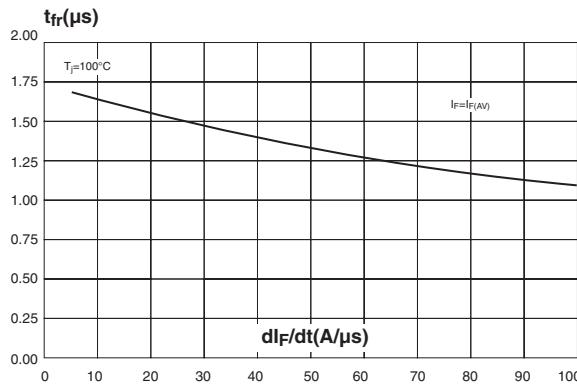


Figure 11: Dynamic parameters versus junction temperature

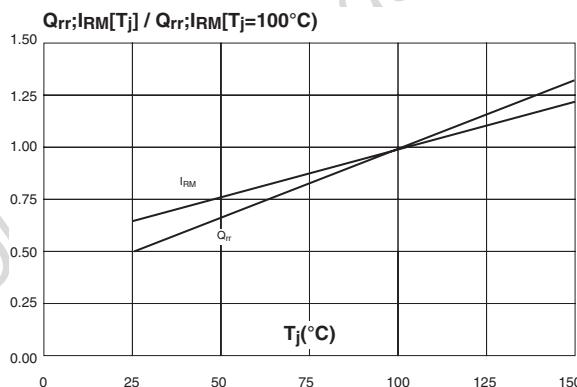


Figure 8: Peak forward voltage versus dI_F/dt (90% confidence)

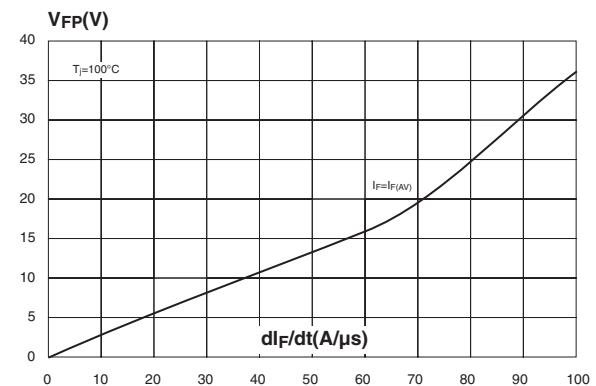


Figure 10: Junction capacitance versus reverse voltage applied (typical values)

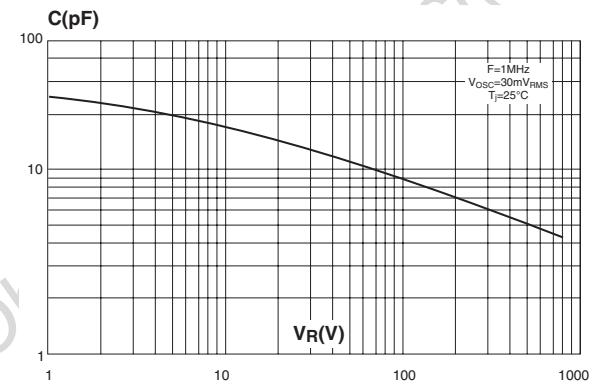
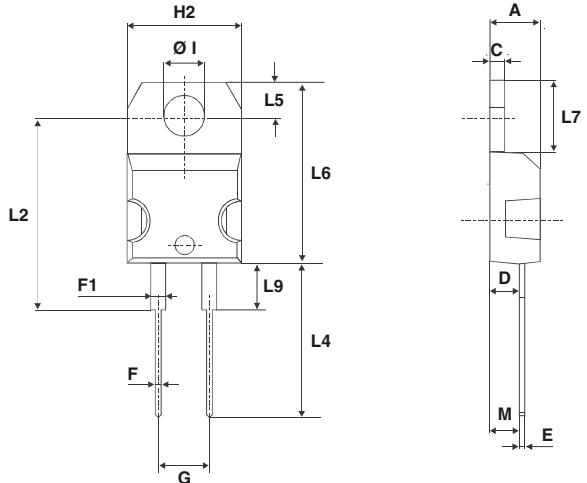


Figure 12: TO-220AC Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Table 7: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
BYW71-800	BYW71800	TO-220AC	1.90 g	50	Tube

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 0.55 m.N. (TO-220AC)
- Maximum torque value: 0.70 m.N. (TO-220AC)

Table 8: Revision History

Date	Revision	Description of Changes
16-Apr-2005	1	First issue.

Obsolete Product(s) - Obsolete Product(s)

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